

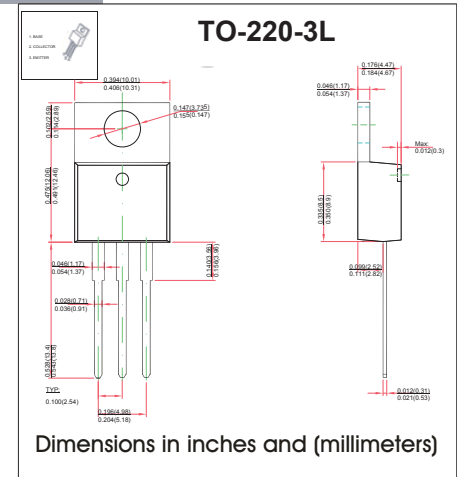
TO-220-3L Plastic-Encapsulate MOSFETS

FEATURES

- N-Channel Power MOSFET
- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete
- Fast Recovery Diode is Characterized for Use in Bridge Circuits
- I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperature

MECHANICAL DATA

- Case style:TO-220-3L molded plastic
- Mounting position:any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	7	A
Pulsed Drain Current	I_{DM}	20	A
Power Dissipation	P_D	2	W
Single Pulsed Avalanche Energy*	E_{AS}	530	mJ
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{stg}	-50 ~ +150	°C

* E_{AS} condition: $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $L=19.5\text{mH}$, $I_L=7\text{A}$, $R_G=0\Omega$

MOSFET ELECTRICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{V}$, $I_D = 250\ \mu\text{A}$)	$V_{(BR)DSS}$	600			V
Drain-Source Leakage Current ($V_{DS} = 600\text{V}$, $V_{GS} = 0\text{V}$) ($V_{DS} = 480\text{V}$, $V_{GS} = 0\text{V}$, $T_J = 125^\circ\text{C}$)	I_{DSS}			1 100	μA
Gate-Source Leakage Current-Forward ($V_{gsf} = 30\text{V}$, $V_{DS} = 0\text{V}$)	I_{GSSF}			100	nA
Gate-Source Leakage Current-Reverse ($V_{gsr} = 30\text{V}$, $V_{DS} = 0\text{V}$)	I_{GSSR}			100	nA
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$)	$V_{GS(th)}$	2.0		4.0	V
Static Drain-Source On-Resistance ($V_{GS} = 10\text{V}$, $I_D = 3.5\text{A}$) *	$R_{D(on)}$			1.3	Ω
Forward Transconductance ($V_{DS} = 50\text{V}$, $I_D = 3.9\text{A}$) *	g_{FS}	5.0			S
Input Capacitance	$(V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$)	C_{iss}	1380	1600	pF
Output Capacitance		C_{oss}	115	190	pF
Reverse Transfer Capacitance		C_{rss}	23	25	pF
Turn-On Delay Time	$(V_{DD} = 300\text{V}$, $I_D = 7.0\text{A}$, $V_{GS} = 10\text{V}$, $R_G = 9.1\Omega$) *	$t_{d(on)}$	30	80	ns
Rise Time		t_r	80	165	ns
Turn-Off Delay Time		$t_{d(off)}$	125	160	ns
Fall Time		t_f	85	120	ns
Total Gate Charge	$(V_{DS} = 480\text{V}$, $I_D = 7.0\text{A}$, $V_{GS} = 10\text{V}$) *	Q_g	38	50	nC
Gate-Source Charge		Q_{gs}	6.4		nC
Gate-Drain Charge		Q_{gd}	15		nC
Internal Drain Inductance (Measured from the drain lead 0.25" from package to center of die)	L_D		4.5		nH
Internal Drain Inductance (Measured from the source lead 0.25" from package to source bond pad)	L_S		7.5		nH

SOURCE-DRAIN DIODE CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Forward On-Voltage(1)	$(I_S = 7.0\text{A}$, $d_S/d_t = 100\text{A}/\mu\text{s}$)	V_{SD}		1.4	V
Forward Turn-On Time		t_{on}	**		ns
Reverse Recovery Time		t_{rr}	415		ns

* Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

** Negligible, Dominated by circuit inductance

RATINGS AND CHARACTERISTIC CURVES

